

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 - Claim 3 (canceled)

Claim 4 (currently amended): A chip carrier plate for carrying a chip, comprising:

a recess;
a first spacer, disposed in the recess, supporting a side of the chip; and
a second spacer, disposed in the recess, supporting another side of the chip;
wherein the height of the first spacer is between 50 μ m and 1000 μ m.

Claim 5 (currently amended): A chip carrier plate for carrying a chip, comprising:

a recess;
a first spacer, disposed in the recess, supporting a side of the chip; and
a second spacer, disposed in the recess, supporting another side of the chip;
wherein the height of the second spacer is between 50 μ m to 1000 μ m.

Claim 6 (currently amended): A chip carrier plate for carrying a chip, comprising:

- a recess;
- a first spacer, disposed in the recess, supporting a side of the chip;
- a second spacer, disposed in the recess, supporting another side of the chip; and
- a third spacer, disposed between the first spacer and the second spacer, and contacting with the chip.

Claim 7 (original): The chip carrier plate as claimed in claim 6, wherein the height of the third spacer is between 50 μ m to 1000 μ m.

Claim 8 (new): A chip carrier plate for carrying a chip, comprising:

- a recess;
- a first protrusion, disposed in the recess, supporting a side of the chip; and
- a second protrusion, disposed in the recess, supporting another side of the chip, the first protrusion and the second protrusion are disposed on opposing sides of the bottom of the recess; and
- a third protrusion, disposed between the first protrusion and the second protrusion, and contacting the chip.

Claim 9 (new): The chip carrier plate as claimed in claim 8, further comprising:

a base;

a protruding face disposed on the base; and

a receiving face formed on the base opposite the protruding face, wherein the recess is

formed on the protruding face.